

Electronic Acknowledgement Receipt

EFS ID:	1342081
Application Number:	10790652
International Application Number:	
Confirmation Number:	9765
Title of Invention:	Nanolayer thick film processing system and method
First Named Inventor/Applicant Name:	Tue Nguyen
Customer Number:	23910
Filer:	Sheldon R. Meyer/Patricia Diehl
Filer Authorized By:	Sheldon R. Meyer
Attorney Docket Number:	TEGL-01162US1
Receipt Date:	29-NOV-2006
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Application Type:	Utility

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part/.zip	Pages (if appl.)
1		Response_to_9-1-06_Office_Action.pdf	214307	yes	6

Multipart Description/PDF files in .zip description			
Document Description	Start	End	
Amendment - After Non-Final Rejection	1	1	
Claims	2	5	
Applicant Arguments/Remarks Made in an Amendment	6	6	

Warnings:

Information:

Total Files Size (in bytes):	214307
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New Applications Under 35 U.S.C. 111
If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371
If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.